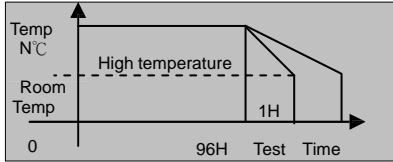
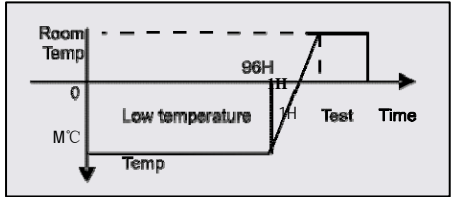
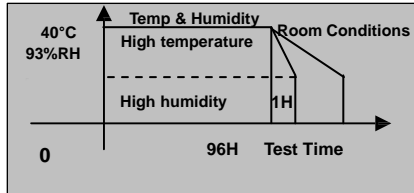
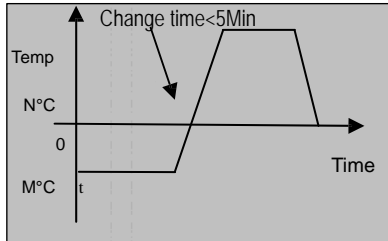
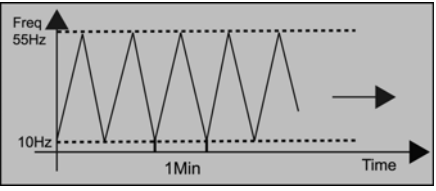
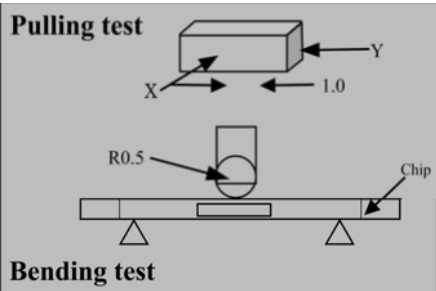


FOR SMT/SMD and other similar types

	Item	Required Characteristics	Test Method / Condition
Environmental tests	<p>High temperature Storage test</p> <p>Reference documents: MIL-STD-202G Method 108A</p>	<ol style="list-style-type: none"> In no case is there a deformation or change in the appearance. $\Delta L/L \leq 10\%$ or 15% $\Delta Q/O \leq 30\%$ $\Delta DCR/DCR \leq 10\%$ 	<p>Temperature: $N \pm 2^\circ\text{C}$ - Time : 96 ± 2 hours Tested not less than 1 hr, or more than 2 hrs at room temperature</p> 
	<p>Low temperature Storage test</p> <p>Reference documents: IEC 68-2-1A 6.1 6.2</p>	<ol style="list-style-type: none"> In no case is there a deformation or change in the appearance.. $\Delta L/L \leq 10\%$ or 15% $\Delta Q/O \leq 30\%$ $\Delta DCR/DCR \leq 10\%$ 	<p>Temperature: $M \pm 2^\circ\text{C}$ Time : 96 ± 2 hours Tested not less than 1 hr, or more than 2 hrs at room temperature</p> 
	<p>Humidity test</p> <p>Reference documents: MIL-STD-202G Method 103B</p>	<ol style="list-style-type: none"> In no case is there a deformation or change in the appearance. $\Delta L/L \leq 10\%$ or 15% $\Delta Q/O \leq 30\%$ $\Delta DCR/DCR \leq 10\%$ 	<p>Temperature: $40^\circ \pm 2^\circ\text{C}$ Humidity: $93 \pm 3\% \text{RH}$ Time : 96 ± 2 hours Tested not less than 1 hr, or more than 2 hrs at room temperature</p> 
	<p>Thermal shock test</p> <p>Reference documents: MIL-STD-202G Method 107G</p>	<ol style="list-style-type: none"> In no case is there a deformation or change in the appearance. $\Delta L/L \leq 10\%$ or 15% $\Delta Q/O \leq 30\%$ $\Delta DCR/DCR \leq 10\%$ <p>For T: weight $\leq 28\text{g}$: 15Min M 28g \leq weight $\leq 136\text{g}$: 30Min N</p>	<p>First $M^\circ\text{C}$ for (t) time, last $N^\circ\text{C}$ for (t) time as 1 cycle. Repeat through 20 cycles.</p> 

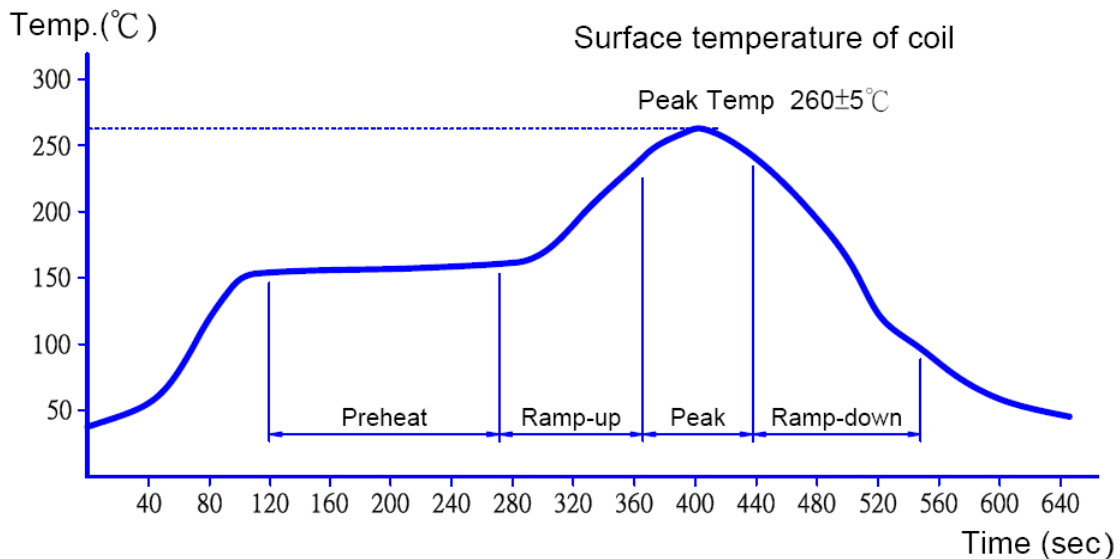
FOR SMT/ SMD and other similar types

	Item	Required Characteristics	Test Method / Condition
Physical characteristic tests	Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002C	Terminals area must have 95% min. Solder coverage	1. Dip the pads in flux and then dip them in a solder pot at 260 ±5°C for 5 seconds. 2. Solder: Lead free 3. Flux: Rosin flux
	Heat endurance of Reflow soldering Reference documents: IPC J-STD-020D	1. In no case is there a deformation or change in the appearance. 2. $\Delta L/L \leq 10\%$ or 15% 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	1. Refer to the next page reflow curve. Repeat 3 times 2. The peak temperature : 260±5°C
	Vibration test Reference documents: MIL-STD-202G Method 201A	1. In no case is there a deformation or change in the appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Apply frequency 10–55Hz. 1.5mm amplitude in each of perpendicular direction for 2 hours(total 6 hours) 
	Drop test Reference documents: MIL-STD-202G Method 203C	1. In no case is there a deformation or change in the appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Packaged & Dropped down from 1m with 981m/s ² (100G) attitude In 1 Angle, 1 Ridge and 2 Surfaces orientations.
	Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: Define: A: sectional area of terminal $0.5\text{mm}^2 < A \leq 1.2\text{mm}^2$ force $\geq 20\text{N}$ time: 10sec $1.2\text{mm}^2 < A$ force $\geq 40\text{N}$ time: 10sec Bending test: Soldering the products on the PCB; after the pulling and bending test, the terminal should not pull off the PCB.	After bending the PCB at the middle point, the deflection shall be 2mm. 
	Resistance to solvent test Reference documents: IEC 68-2-45:1993	In no case is there a deformation or change in the appearance or an obliteration of the marking.	Dip parts into an IPA solvent for 5±0.5Min, then dry them at room temperature for 5Min. and brush the marking 10 times.

FOR SMT/SMD and other similar types

	Item	Required Characteristics	Test Method / Condition
Electrical Characteristic tests	Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
	Overload test Reference documents JIS C5311-6.13	1. During the test: there should be no smoke, no peculiar smell and no fire. 2. The characteristics should be normal after the test.	Apply twice at rated the current for 5 minutes. (It's not an application for some special designs)
	Voltage resistance test Reference documents: MIL-STD-202G Method 301	1. During the test there should be no breakdown 2. The characteristics should be normal after the test	1. For parts with two coils 2. DC1000V, Current: 1mA, Time: 1Min.

Curve of Heat endurance of the Reflow soldering test



1. This peak temperature is only applicable to some specific parts. The operating parameter may vary according to the part type.
2. The test is made under the conditions mentioned above and is left for 1 hour in normal temperature and humidity. After that; mechanical or electrical defeat should be found.
4. The reflow conditions are according to the equipment used by our manufacturing facilities.

NOTE: The above specifications are only for reference; follow the confirmation documents for the specific test conditions.